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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10066783	FILING DATE 02/06/2002	CLASS 432 297	SUBCLASS 87	GAU 3749	EXAMINER Greg Wilson
**APPLICANTS: Kawase Yoshimasa;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-036040 02/13/2001					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 025311-0115	
TITLE : Wafer heat-treatment system and wafer heat-treatment method					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims <input type="checkbox"/> Print Claim for O.G. <input type="checkbox"/>
ISSUE FEE		Primary Examiner	DRAWING
Amount Due	Date Paid		Sheets Drwg. <input type="checkbox"/> Figs. Drwg. <input type="checkbox"/> Print Fig. <input type="checkbox"/>
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner
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